PART INFORMATION	
Mfg Item Number	MKW31Z256VHT4
Mfg Item Name	LamQFN 48 7*7*0.98 P0.5

SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-06-10
Response Document ID	00HZK00165D053A1.6
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION	
EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	
EU RoHS Exemption(s)	

MANUFACTURING	
Mfg Item Number	MKW31Z256VHT4
Mfg Item Name	LamQFN 48 7*7*0.98 P0.5
Version	ALL
Weight	0.089500
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight
	6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight
	6(c) : Copper alloy containing up to 4% lead by weight
	7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
	7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications
	7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
	7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
	7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC
	7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors
	15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Non-Conductive Epoxy/Adhesive	0.0013						g					
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.0000975	g	75000	7.5		1089	0.1089
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Crosslinked acrylate polymer	25767-43-5		0.00026	g	200000	20		2905	0.2905
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Other polymers	-		0.0000975	g	75000	7.5		1089	0.1089
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other polymers	-		0.00026	g	200000	20		2905	0.2905
Non-Conductive Epoxy/Adhesive		Glass	Silica, vitreous	60676-86-0		0.000585	g	450000	45		6536	0.6536
Die Encapsulant, Halogen-free	0.052						g					
Die Encapsulant, Halogen-free		Metals	Other aluminum compounds	-		0.00156	g	30000	3		17430	1.743
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00052	g	10000	1		5810	0.581
Die Encapsulant, Halogen-free		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.00156	g	30000	3		17430	1.743
Die Encapsulant, Halogen-free		Plastics/polymers	Other phenolic resins	-		0.00156	g	30000	3		17430	1.743
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0		0.0442	g	850000	85		493866	49.3866
Die Encapsulant, Halogen-free		Plastics/polymers	Other Non-halogenated Epoxy resins	-		0.0026	g	50000	5		29050	2.905
Organic Substrate, Halogen-fre	0.029						g					
Organic Substrate, Halogen-fre		Solvents, additives, and other materials	Other aromatic amines and their salts	-		0.00000861	g	297	0.0297		96	0.0096
Organic Substrate, Halogen-fre		Metals	Barium sulfate	7727-43-7		0.00029041	g	10014	1.0014		3244	0.3244
Organic Substrate, Halogen-fre		Metals	Copper, metal	7440-50-8		0.01350109	g	465555	46.5555		150850	15.085
Organic Substrate, Halogen-fre		Plastics/polymers	Other Epoxy resins	-		0.00123549	g	42603	4.2603		13804	1.3804
Organic Substrate, Halogen-fre		Metals	Gold, metal	7440-57-5		0.00068742	g	23704	2.3704		7680	0.768
Organic Substrate, Halogen-fre		Metals	Talc	14807-96-6		0.00014625	g	5043	0.5043		1634	0.1634
Organic Substrate, Halogen-fre		Nickel (external applications only)	Nickel	7440-02-0		0.00536454	g	184984	18.4984		59938	5.9938
Organic Substrate, Halogen-fre		Glass	Fibrous-glass-wool	65997-17-3		0.00549106	g	189347	18.9347		61352	6.1352
Organic Substrate, Halogen-fre		Glass	Silicon dioxide	7631-86-9		0.00096988	g	33444	3.3444		10836	1.0836
Organic Substrate, Halogen-fre		Solvents, additives, and other materials	Other Aromatic carbonyl compounds	-		0.0000544	g	1876	0.1876		607	0.0607
Organic Substrate, Halogen-fre		Metals	Copper phthalocyanine	147-14-8		0.00000258	g	89	0.0089		28	0.0028
Organic Substrate, Halogen-fre		Solvents, additives, and other materials	Quinacridone pigment	1047-16-1		0.00000258	g	89	0.0089		28	0.0028
Organic Substrate, Halogen-fre		Solvents, additives, and other materials	3-methoxy-3-methyl-1-butyl acetate	103429-90-9		0.0003183	g	10976	1.0976		3556	0.3556
Organic Substrate, Halogen-fre		Plastics/polymers	Epoxy Resin	115254-47-2		0.00092481	g	31890	3.189		10333	1.0333
Organic Substrate, Halogen-fre		Solvents, additives, and other materials	1,2,4-Trimethylbenzene	95-63-6		0.00000258	g	89	0.0089		28	0.0028
Bonding Wire, PdCu	0.0002						g					
Bonding Wire, PdCu		Metals	Copper, metal	7440-50-8		0.0001962	g	981000	98.1		2192	0.2192
Bonding Wire, PdCu		Metals	Gold, metal	7440-57-5		0.0000002	g	1000	0.1		2	0.0002
Bonding Wire, PdCu		Metals	Palladium, metal	7440-05-3		0.0000036	g	18000	1.8		40	0.004
Silicon Semiconductor Die	0.007						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.00014	g	20000	2		1564	0.1564
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.00686	g	980000	98		76648	7.6648

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MKW31Z256VHT4_IPC1752_v11.xml

http://www.freescale.com/mcds/MKW31Z256VHT4_IPC1752A.xml